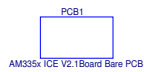


# ***AM335X\_ICE Board***

- See the Hardware Implementation Document for design details
- See the Hardware User Guide for board details
- See the PCB Build Specification for PCB Details



TIDEP0053

<b>ARM MPU</b>	<b>Texas Instruments, Inc.</b>			
	ARM MPU Business Unit 12500 TI Blvd Dallas, TX 75243			
	TMDXICE3359			
	Title			
Size	Document Number	Modified By:	Rev	
C	AM335X_ICE_3H0013_2V1A.dsn	Rachna	2.1A	
Date: Wednesday, April 17, 2013		Sheet: 1	of 15	





AM335X

AM335X  
15mm x 15mm Package

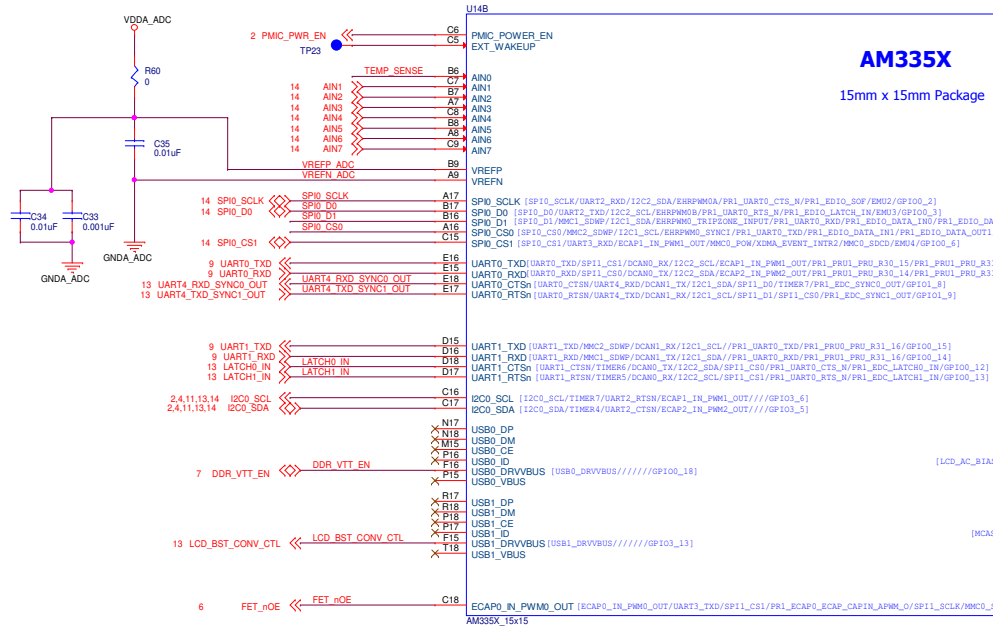
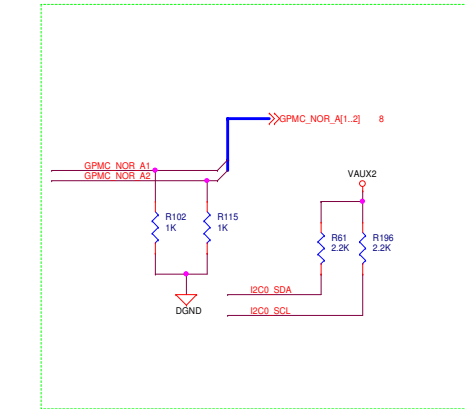
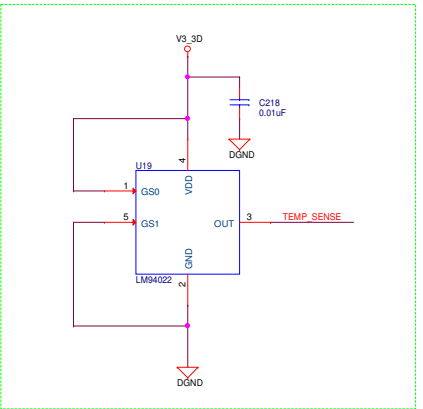


Table of pin connections for the AM335X processor, listing pin numbers, processor pin names, and board pin names with their respective functions.

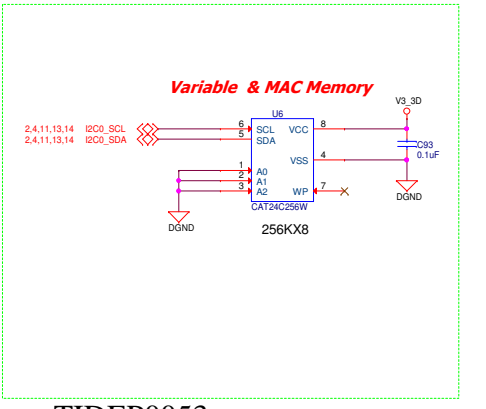
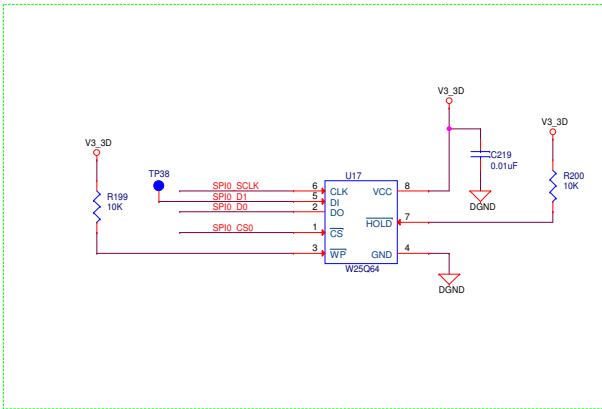
TEMPERATURE SENSOR



SPI FLASH



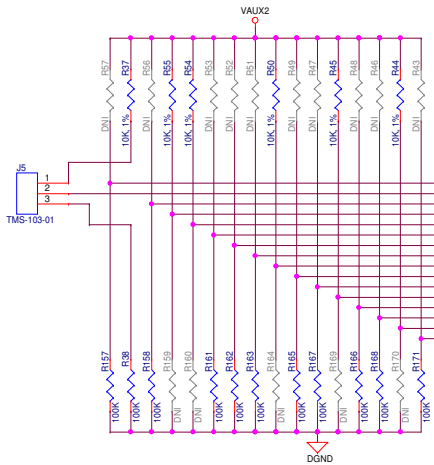
BOARD ID EEPROM



TIDEP0053 Texas Instruments, Inc. ARM MPU Business Unit 1500 TI Blvd Dallas, TX 75243 TMDXICE3359 AM335X 2 Of 3

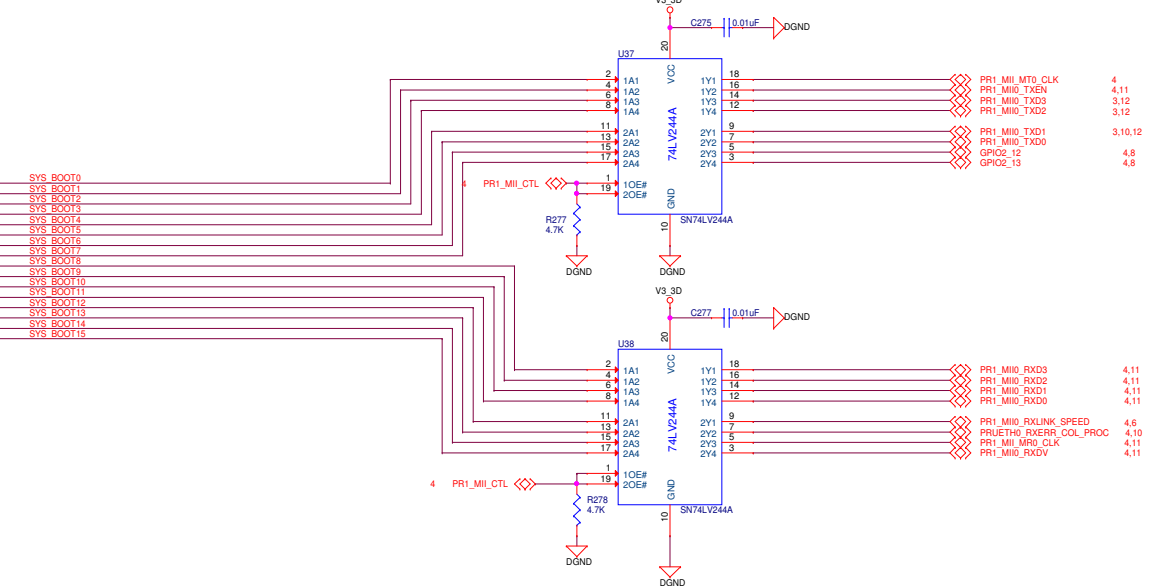


### BOOT CONFIGURATION

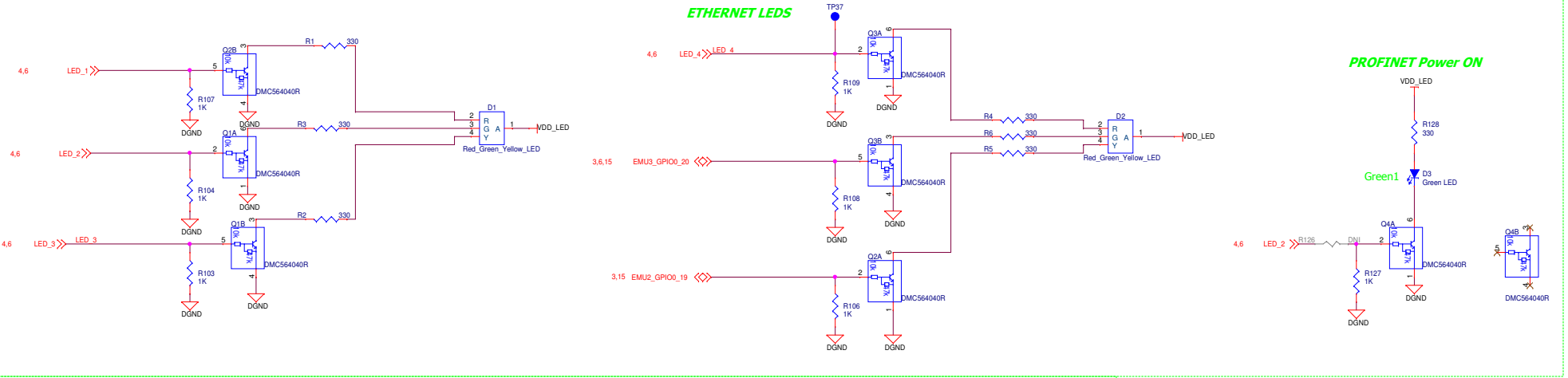


Check Hardware User's Guide for Boot Sequence Details

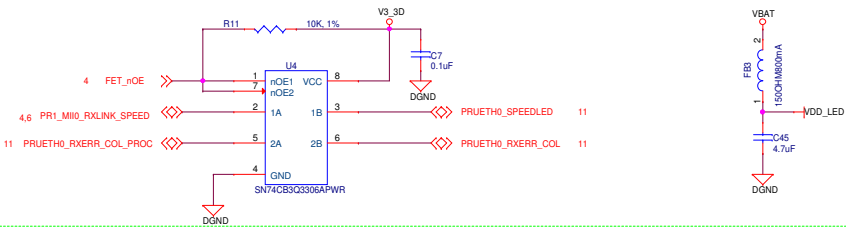
### SYS BOOT BUFFERS



### ETHERNET LEDS



### FET SWITCH



**TIDEP0053**

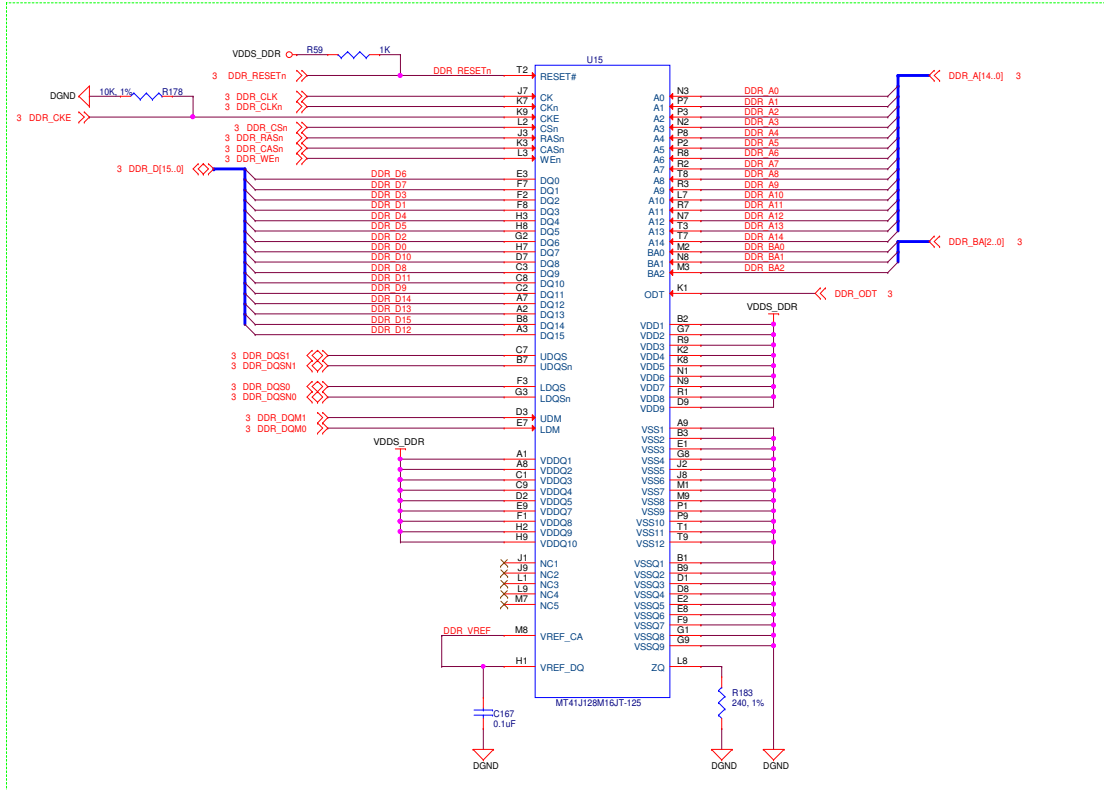
**ARM MPU** **Texas Instruments, Inc.**

ARM MPU Business Unit  
12500 TI Blvd  
Dallas, TX 75243

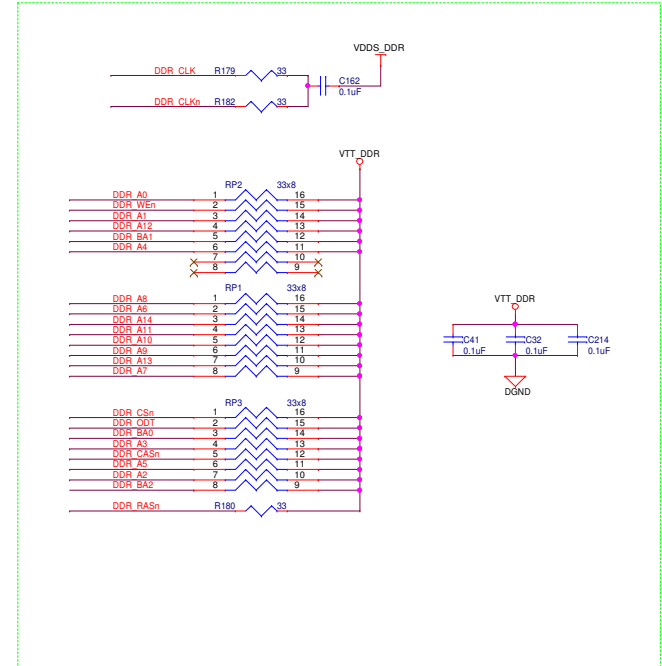
**TMDXICE3359**  
SYSBOOT CONFIG & ETHERCAT LEDS

Size	Document Number	Modified By:	Rev
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Date:	Wednesday, April 17, 2013	Sheet:	6 of 15

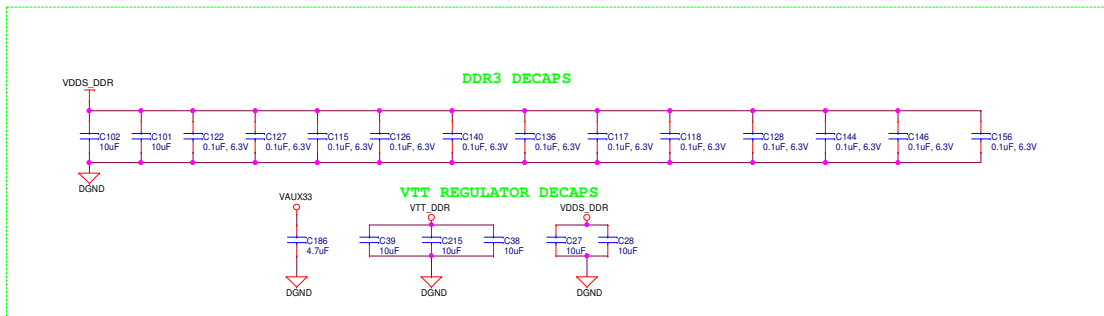
### DDR3 SDRAM



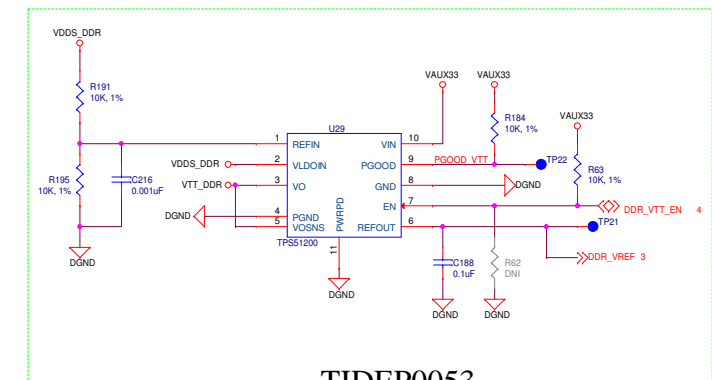
### Terminations



### DECAPS



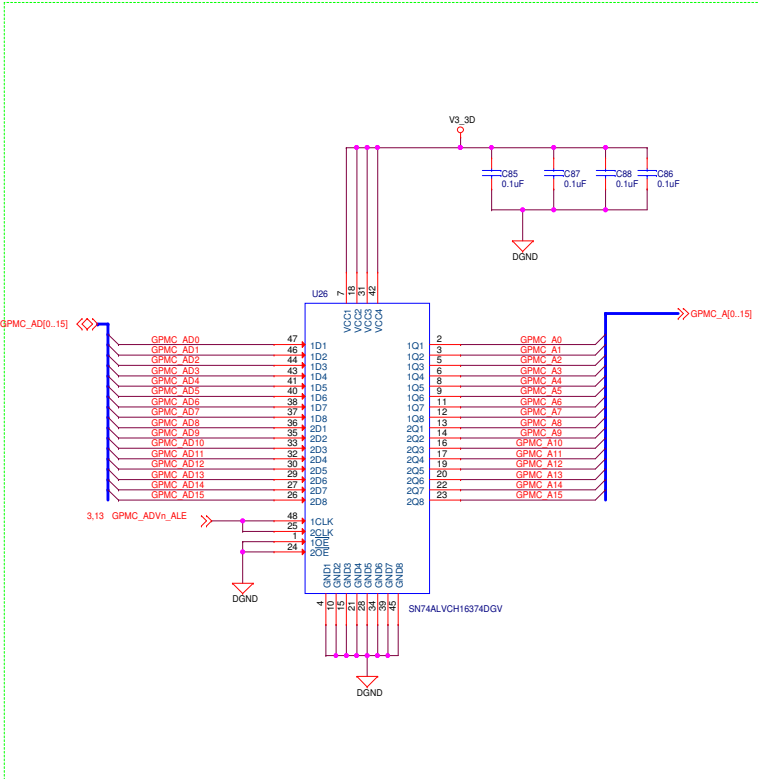
### VTT REGULATOR



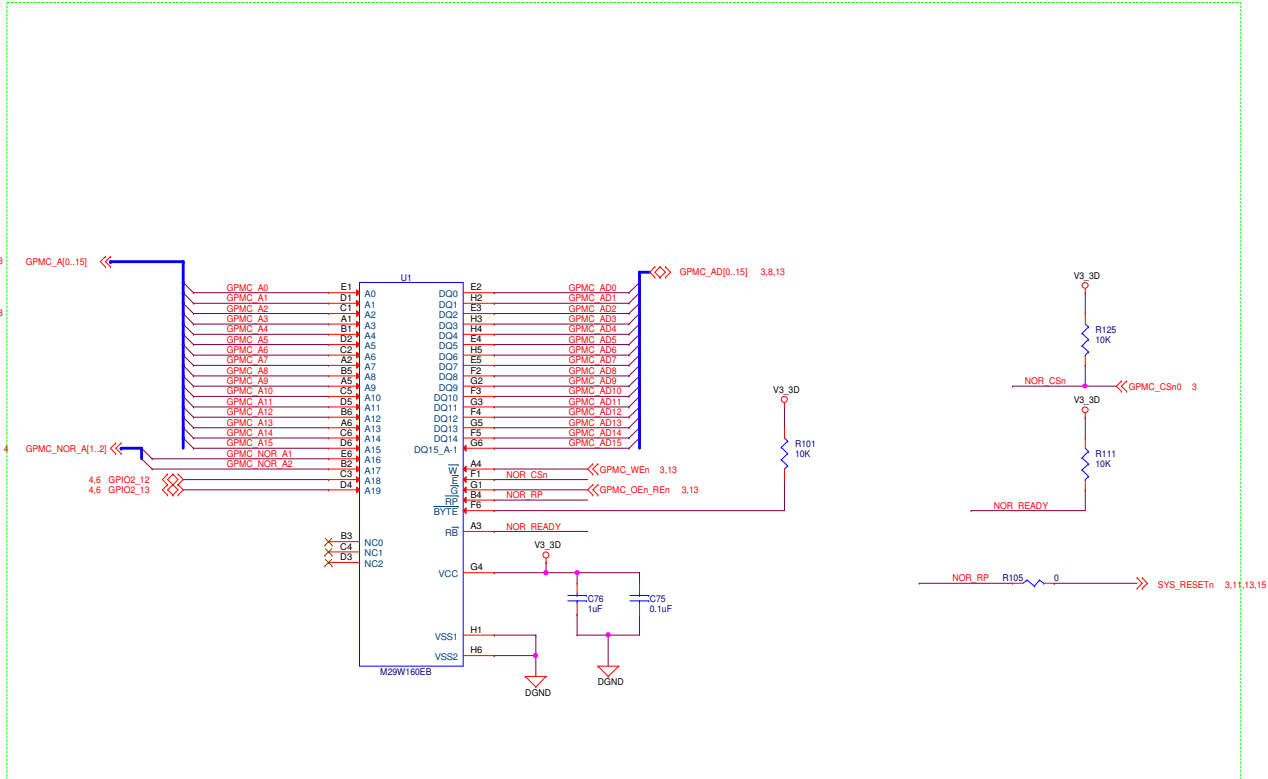
TIDEP0053

<b>ARM MPU</b>	<b>Texas Instruments, Inc.</b>		<b>TEXAS INSTRUMENTS</b>
	ARM MPU Business Unit 12500 TI Blvd Dallas, TX 75243		
<b>TMDXICE359</b>			
DDR3 Memory			
Size	Document Number	Modified By:	Rev
C	AM335X_ICE_3H0013_2V1A.dsn	Rachna	2.1A
Date:	Wednesday, April 17, 2013	Sheet: 7	of 15

**D FLIPFLOP**



**NOR FLASH**

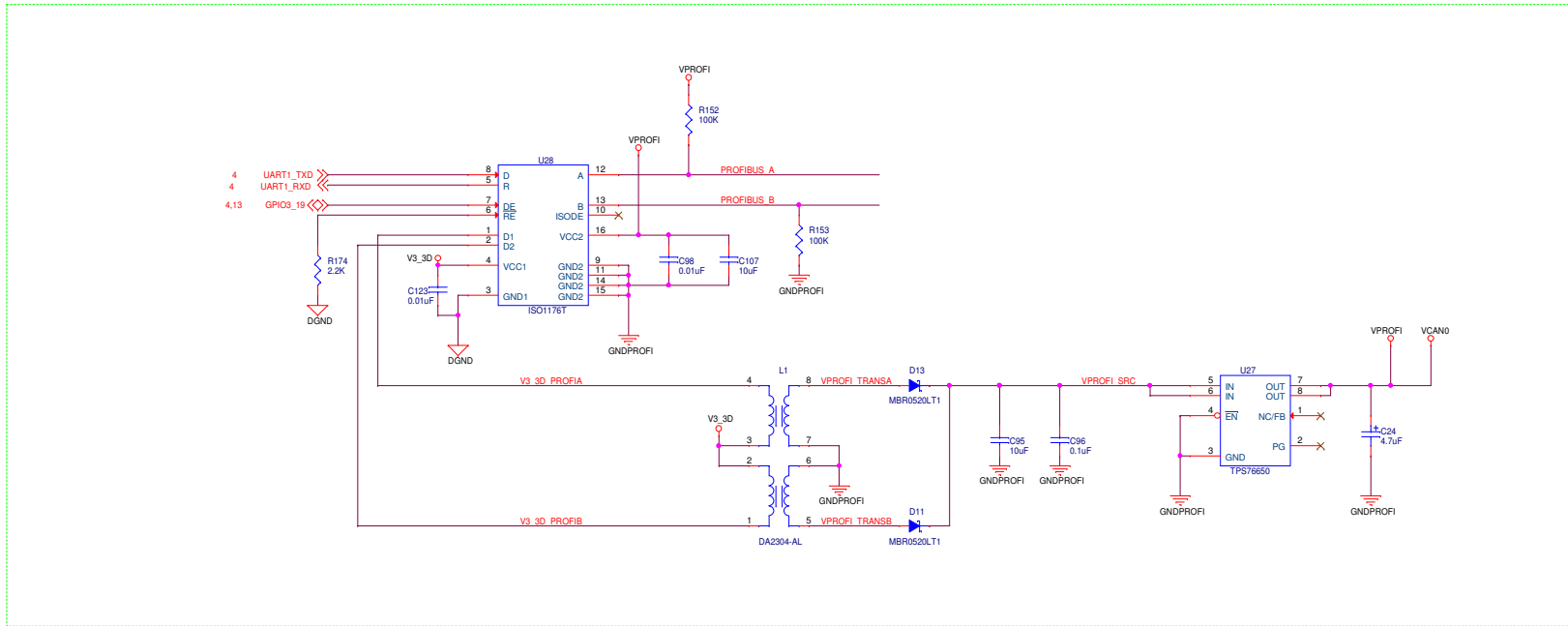


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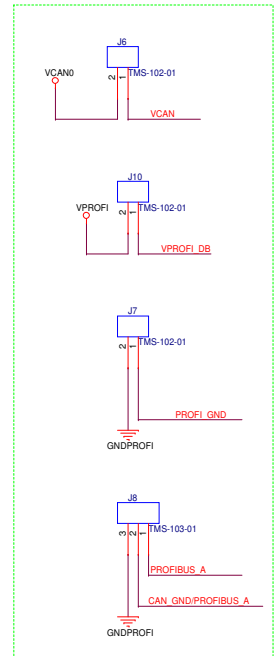
<b>ARM MPU</b>	<b>Texas Instruments, Inc.</b>		
	ARM MPU Business Unit 12500 TI Blvd Dallas, TX 75243		
	TMDXICE3359 NOR FLASH INTERFACE		
	Size C	Document Number AM335X_ICE_3H0013_2V1A.dsn	Modified By Radha
Date: Wednesday, April 17, 2013	Sheet: 6 of 15		



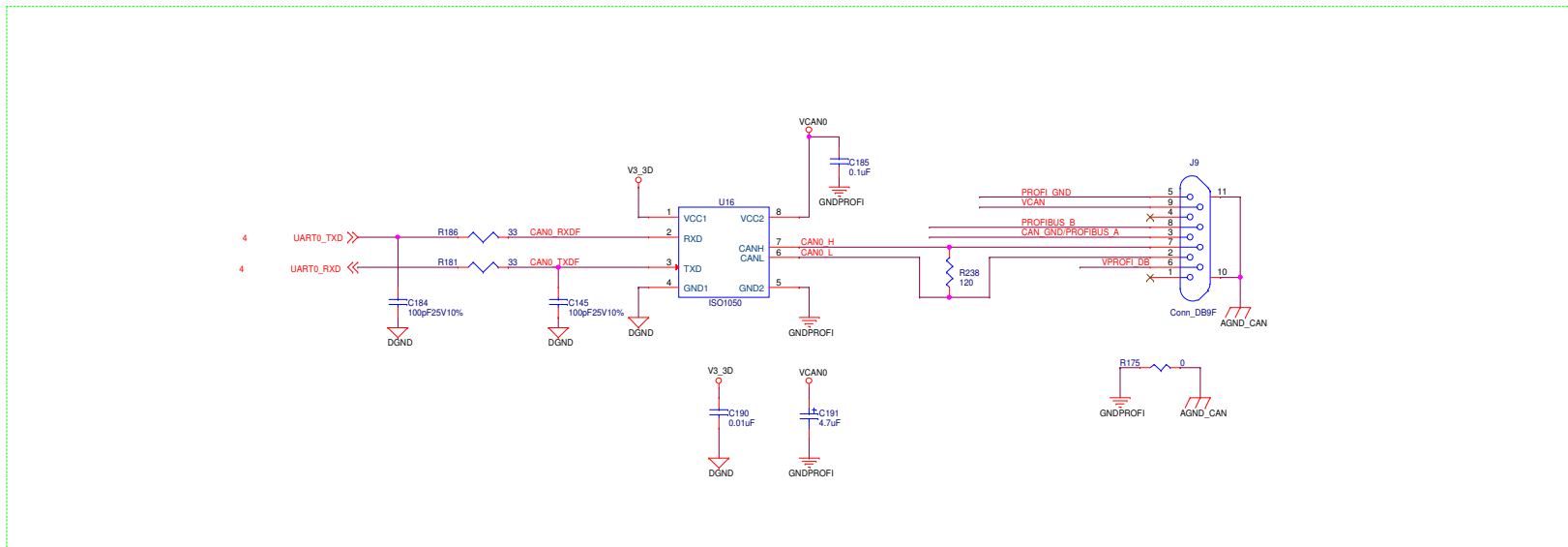
**PROFIBUS**



**CAN / PROFIBUS SELECTION**



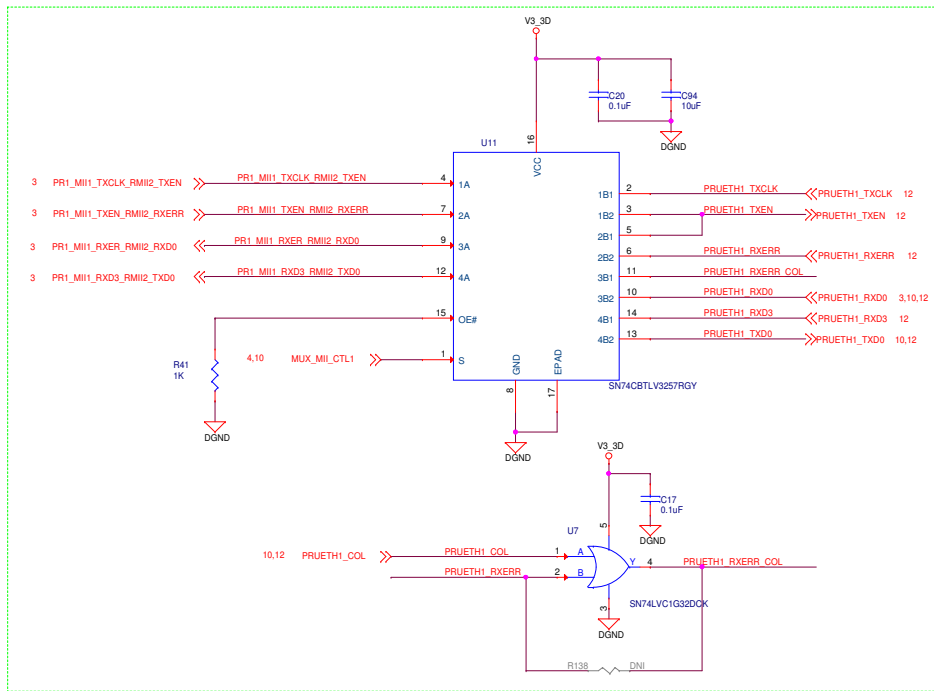
**CAN PORT**



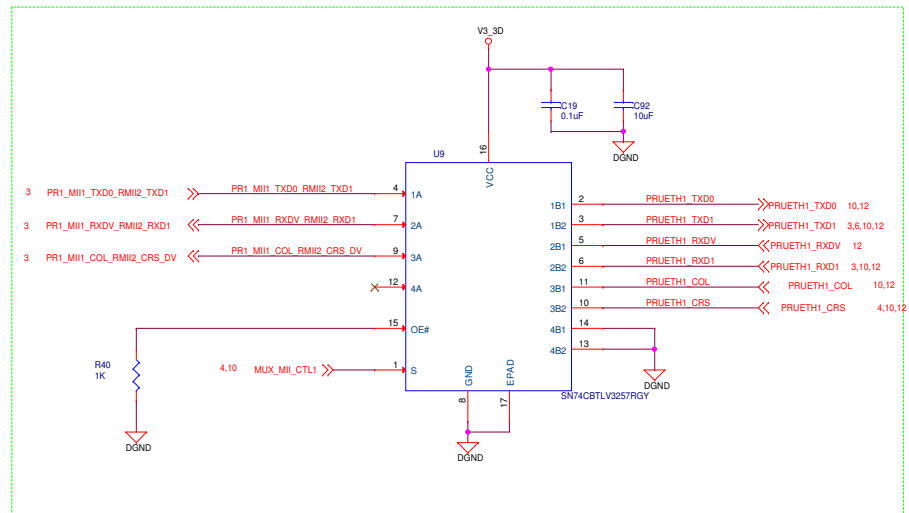
TIDEP0053

<b>ARM MPU</b>	<b>Texas Instruments, Inc.</b>			
	ARM MPU Business Unit 12500 TI Blvd Dallas, TX 75243			
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	Size	Document Number	Modified By:	Rev
C	AM335X_ICE_3H0013_2V1A.dsn	Rachna	2.1A	
Date: Wednesday, April 17, 2013			Sheet: 9 of 15	

**MI11\_MUX1**



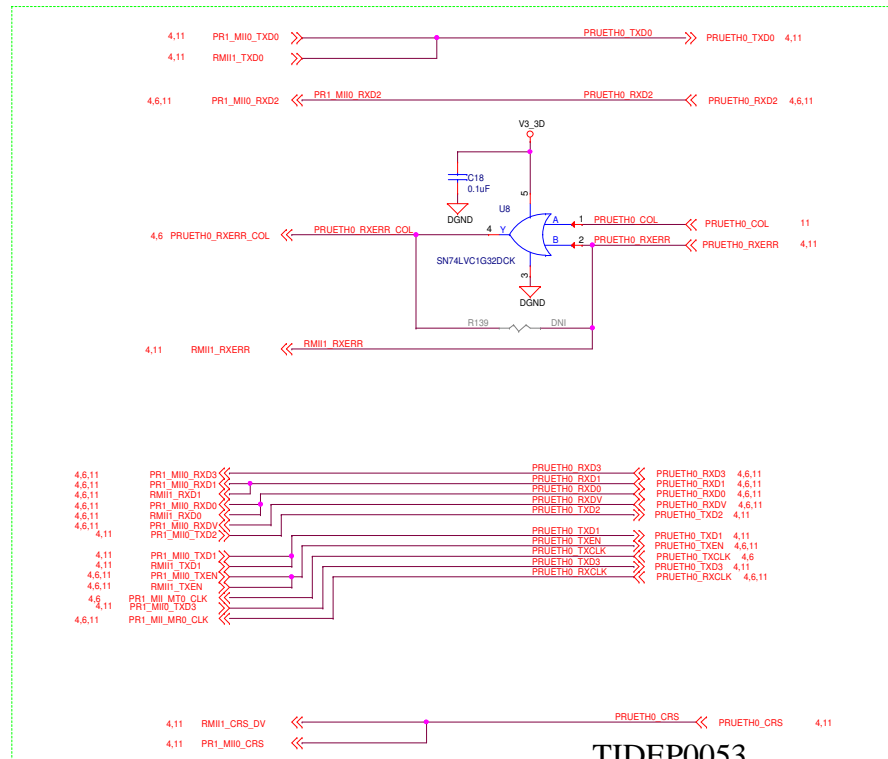
**MI11\_MUX2**



**MI11\_MUX**



**MI10\_MUX**



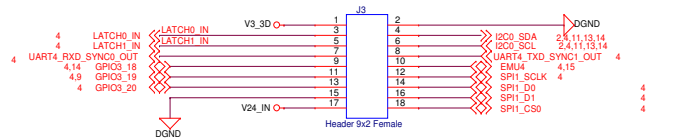
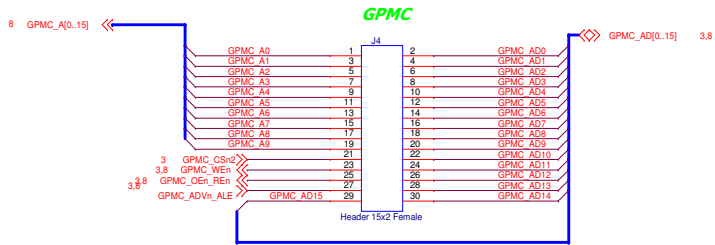
TIDEP0053

<b>ARM MPU</b>	<b>Texas Instruments, Inc.</b>		
	ARM MPU Business Unit 12500 TI Blvd Dallas, TX 75243		
<b>TMDXICE3359</b>			
PRU_CPSW_ETHERNET_MUX			
Size	Document Number	Modified By:	Rev
C	AM335X_ICE_3H0013_2V1A.dsn	Rachna	2.1A
Date:	Wednesday, April 17, 2013	Sheet: 10	of 15

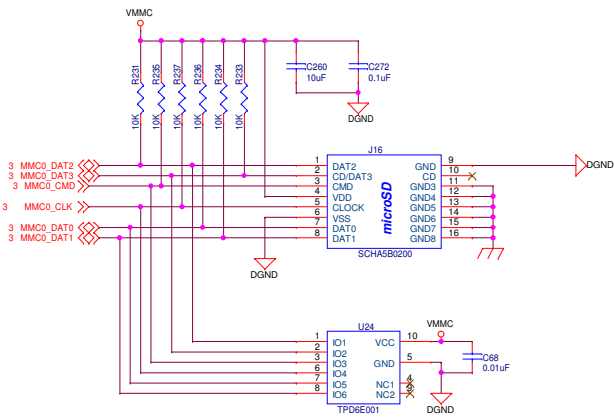




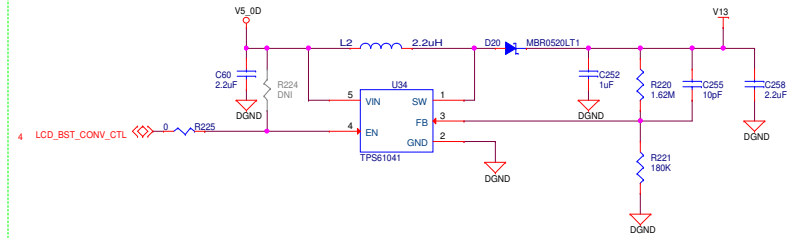
### HOST EXPANSION HEADERS



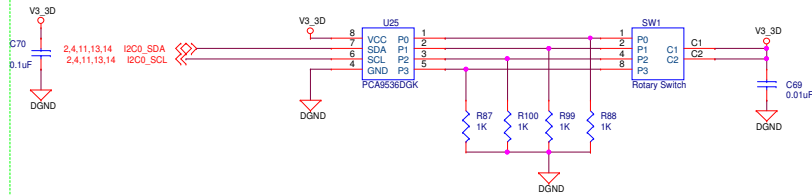
### MICRO SD CARD SOCKET



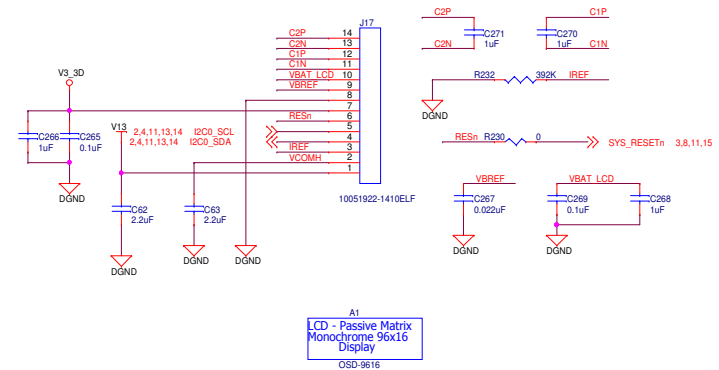
### 5V TO 13V BOOST CONVERTER



### ROTARY SWITCH - INDUSTRIAL ETHERNET SLAVE ADDRESS SELECTOR



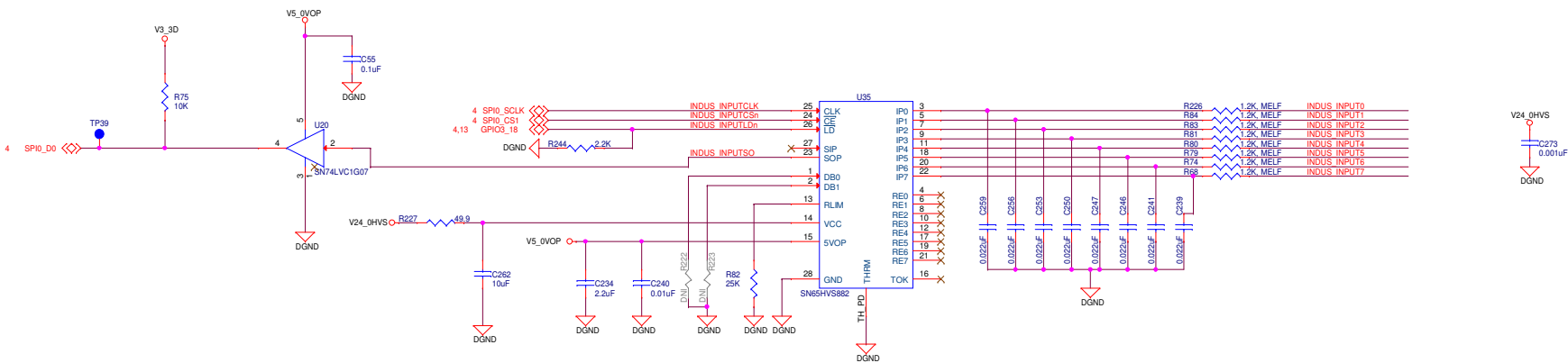
### MONOCHROME LCD INTERFACE



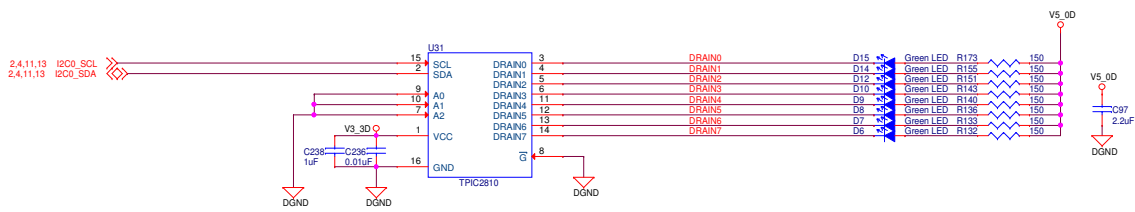
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<b>ARM MPU</b>	<b>Texas Instruments, Inc.</b>		
	ARM MPU Business Unit 12500 TI Blvd Dallas, TX 75243		
	TMDXICE3359 HOST EXPANSION & MMC0 & LCD		
	Size C	Document Number AM335X_ICE_3H0013_2V1A.dsn	Modified By: Radha
Date: Wednesday, April 17, 2013			Sheet: 13 of 15

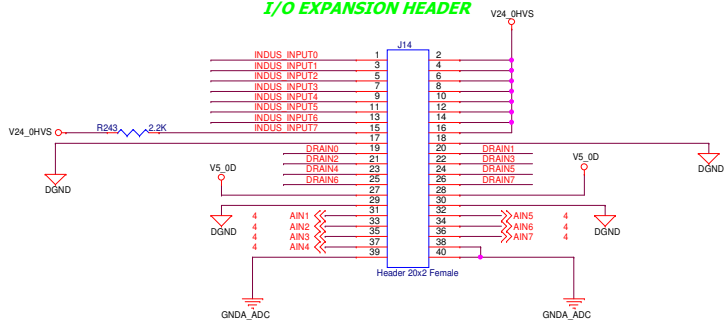
### DIGITAL INPUTS



### DIGITAL OUTPUTS



### I/O EXPANSION HEADER



TIDEP0053

<b>ARM MPU</b>	<b>Texas Instruments, Inc.</b>			
	ARM MPU Business Unit 15200 TI Blvd Dallas, TX 75243			
	TMDXICE3359 Industrial Inputs/Outputs			
	Size C	Document Number AM335X_JCE_3H0013_2V1A.dsn	Modified By Radha	Rev 2.1A
	Date: Wednesday, April 17, 2013		Sheet: 14	of 15



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